

R1LP0108E Series

1Mb Advanced LPSRAM (128k word x 8bit)

R10DS0151EJ0100 Rev.1.00 2013.6.21

Description

The R1LP0108E Series is a family of low voltage 1-Mbit static RAMs organized as 131,072-word by 8-bit, fabricated by Renesas's high-performance 0.15um CMOS and TFT technologies. The R1LP0108E Series has realized higher density, higher performance and low power consumption. The R1LP0108E Series is suitable for memory applications where a simple interfacing, battery operating and battery backup are the important design objectives. It has been packaged in 32-pin SOP,32-pin TSOP and 32-pin sTSOP.

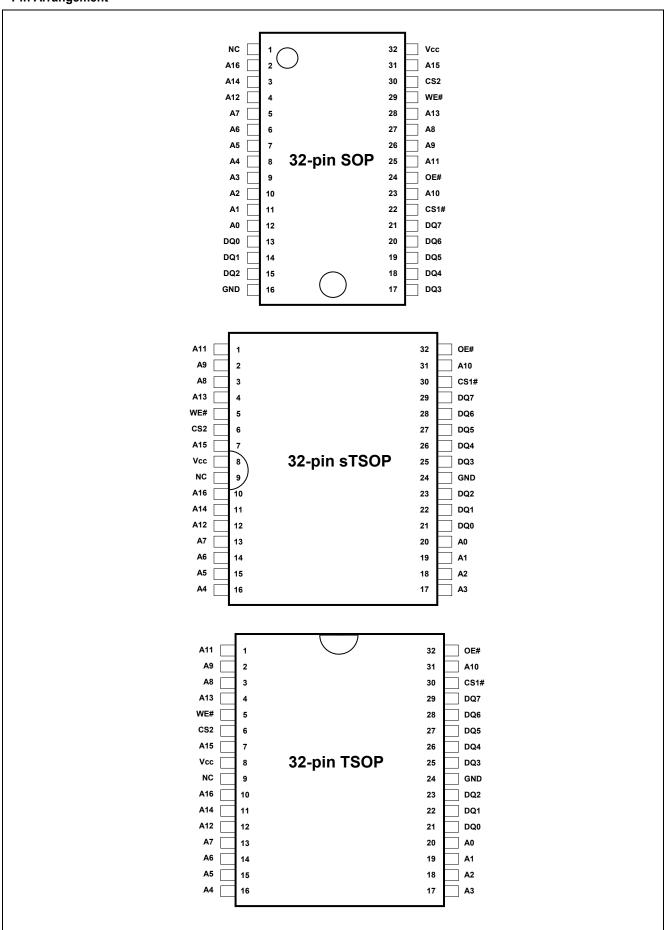
Features

- Single 4.5~5.5V power supply
- Small stand-by current: 0.6µA (5.0V, typical)
- No clocks, No refresh
- All inputs and outputs are TTL compatible.
- Easy memory expansion by CS1# and CS2
- Common Data I/O
- Three-state outputs: OR-tie Capability
- OE# prevents data contention on the I/O bus

Ordering Information

Orderable Part Name	Access time	Temperature Range	Package	Shipping Container	Quantity	
R1LP0108ESN-5SR#B*	EE no	0 ~ +70°C				
R1LP0108ESN-5SI#B*	55 ns	-40 ~ +85°C		Tuba	Max. 25pcs/Tube	
R1LP0108ESN-7SR#B*	70 ns	0 ~ +70°C	525-mil 32-pin	Tube	Max. 225pcs/Inner Bag Max. 900pcs/Inner Box	
R1LP0108ESN-7SI#B*	70118	-40 ~ +85°C	plastic SOP		·	
R1LP0108ESN-5SR#S*	EE no	0 ~ +70°C	PRSP0032DF-A			
R1LP0108ESN-5SI#S*	55 ns	-40 ~ +85°C	(32P2S-A)	Embossed	1000nco/Dool	
R1LP0108ESN-7SR#S*	70 ns	0 ~ +70°C		tape	1000pcs/Reel	
R1LP0108ESN-7SI#S*	70 ns	-40 ~ +85°C				
R1LP0108ESA-5SR#B*	<i>FF</i>	0 ~ +70°C				
R1LP0108ESA-5SI#B*	55 ns	-40 ~ +85°C		Two	Max. 234pcs/Tray	
R1LP0108ESA-7SR#B*	70	0 ~ +70°C	8mm×13.4mm 32-pin plastic sTSOP	Tray	Max. 1872pcs/Inner Box	
R1LP0108ESA-7SI#B*	70 ns	-40 ~ +85°C	(normal-bend type)			
R1LP0108ESA-5SR#S*	- 55 ns	0 ~ +70°C		Embossed		
R1LP0108ESA-5SI#S*	55 118	-40 ~ +85°C	PTSA0032KB-A (32P3K-B)		1000mas/Dagl	
R1LP0108ESA-7SR#S*	70	0 ~ +70°C	(021 01(B)	tape	1000pcs/Reel	
R1LP0108ESA-7SI#S*	70 ns	-40 ~ +85°C				
R1LP0108ESF-5SR#B*	<i>FF</i>	0 ~ +70°C				
R1LP0108ESF-5SI#B*	55 ns	-40 ~ +85°C		T	Max. 156pcs/Tray	
R1LP0108ESF-7SR#B*	70	0 ~ +70°C	8mm×20mm 32-pin plastic TSOP	Tray	Max. 1248pcs/Inner Box	
R1LP0108ESF-7SI#B*	70 ns	-40 ~ +85°C	(normal-bend type)			
R1LP0108ESF-5SR#S*	55	0 ~ +70°C				
R1LP0108ESF-5SI#S*	55 ns	-40 ~ +85°C	PTSA0032KA-A (32P3H-E)	Embossed	1000maa/Daal	
R1LP0108ESF-7SR#S*	70	0 ~ +70°C	(021 011-L)	tape	1000pcs/Reel	
R1LP0108ESF-7SI#S*	70 ns	-40 ~ +85°C				

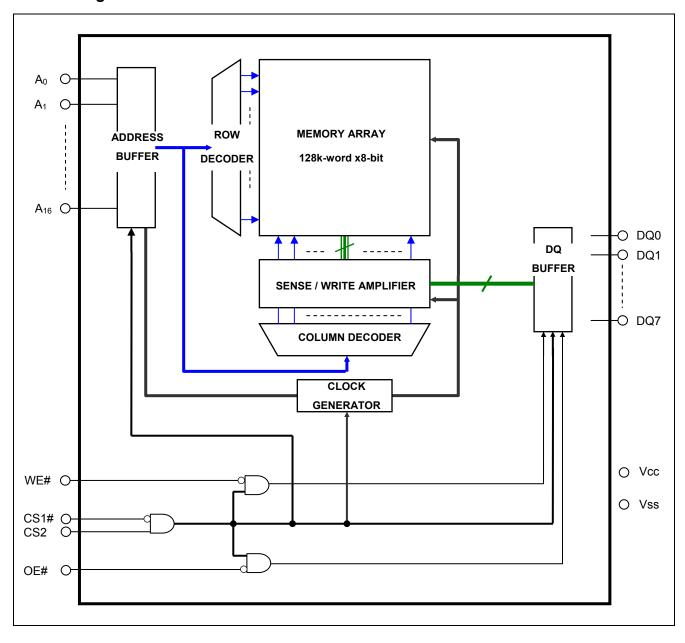
Pin Arrangement



Pin Description

Pin name	Function
Vcc	Power supply
Vss	Ground
A0 to A16	Address input
DQ0 to DQ7	Data input/output
CS1#	Chip select 1
CS2	Chip select 2
WE#	Write enable
OE#	Output enable
NC	Non connection

Block Diagram



Operation Table

CS1#	CS2	WE#	OE#	DQ0~7	Operation
Х	L	Х	Х	High-Z	Stand-by
Н	Х	Х	Х	High-Z	Stand-by
L	Н	L	Х	Din	Write
L	Н	Н	L	Dout	Read
L	Н	Н	Н	High-Z	Output disable

Note 1. H: V_{IH} L:V_{IL} X: V_{IH} or V_{IL}

Absolute Maximum

Parameter	Symbol	Va	lue	unit	
Power supply voltage relative to Vss	Vcc	-0.3 to +7		V	
Terminal voltage on any pin relative to Vss	V _T	-0.3 ^{*1} to	-0.3 ^{*1} to Vcc+0.3 ^{*2}		
Power dissipation	P _T	0.7		W	
Operation to an exeture	Topr*3	R Ver.	0 to +70	°C	
Operation temperature	ropr	I Ver.	-40 to +85		
Storage temperature range	Tstg	-65 to 150		°C	
Ctorono torono restricto manage under bios	Tbias*3	R Ver.	0 to +70	°C	
Storage temperature range under bias	Iblas	I Ver.	-40 to +85		

Note 1. -

- 1. -3.0V for pulse ≤ 30ns (full width at half maximum)
- 2. Maximum voltage is +7V.
- 3. Ambient temperature range depends on R/I-version. Please see table on page 1.

DC Operating Conditions

Parameter		Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage		Vcc	4.5	5.0	5.5	V	
		Vss	0	0	0	V	
Input high voltage		V _{IH}	2.2	-	Vcc+0.3	V	
Input low voltage		V_{IL}	-0.3	1	0.8	V	1
Ambient temperature range	R Ver.	To	0	ı	+70	°C	2
Ambient temperature range	I Ver.	Та	-40	-	+85	°C	2

Note 1. -3.0V for pulse ≤ 30 ns (full width at half maximum)

DC Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit		Test conditions
Input leakage current	I _{LI}	-	-	1	μΑ	Vin = Vss	to Vcc
Output leakage current	I _{LO}	-	-	1	μА	CS1# =V _{IH} OE# =V _{IH} , VI/O =Vss	or CS2 =V _{IL} or to Vcc
Average operating current	I _{CC1}	-	25	35	mA		duty =100%, $II/O = 0mA$, $CS2 = V_{IH}$, Others = V_{IH}/V_{IL}
	I _{CC2}	-	2	5	mA	CS1# ≤ 0.2	s, duty =100%, II/O = 0mA 2V, CS2 ≥ Vcc-0.2V, 0.2V, V _{IL} ≤ 0.2V
Standby current	I _{SB}	-	-	3	mA	"CS2 =V _{IL} " "CS2 = V _I H Others = V	and CS1# =V _{IH} ",
Standby current		-	0.6*1	2	μА	~+25°C	Vin = Vss to Vcc
	lan.	-	-	3	μА	~+40°C	(1) CS2 ≤ 0.2 or (2) CS1#≥ Vcc-0.2V,
	I _{SB1}	-	-	8	μА	~+70°C	CS2 ≥ Vcc-0.2V
		-	-	10	μА	~+85°C	
Output high voltage	V _{OH}	2.4	-	-	V	I _{OH} = -1mA	
	V _{OH2}	Vcc - 0.5	-		V	I _{OH} = -0.1n	nA
Output low voltage	V _{OL}	-	-	0.4	V	I _{OL} = 2mA	

Note 1. Typical parameter indicates the value for the center of distribution at 5.0V (Ta= 25°C), and not 100% tested.

Capacitance

 $(Vcc = 4.5V \sim 5.5V, f = 1MHz, Ta = 0 \sim +70^{\circ}C / -40 \sim +85^{\circ}C^{*2})$

	•						
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions	Note
Input capacitance	C in	-	-	8	pF	Vin =0V	1
Input / output capacitance	C _{I/O}	-	-	10	pF	VI/O =0V	1

Note 1. This parameter is sampled and not 100% tested.

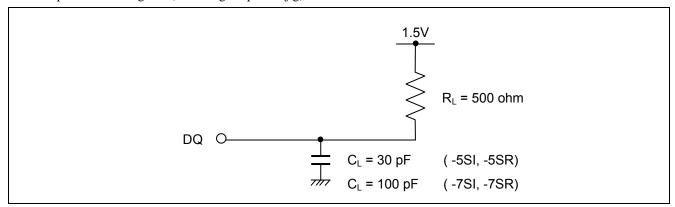
2. Ambient temperature range depends on R/I-version. Please see table on page 1.

^{2.} Ambient temperature range depends on R/I-version. Please see table on page 1.

AC Characteristics

Test Conditions (Vcc = 4.5V ~ 5.5V, Ta = $0 \sim +70^{\circ}\text{C} / -40 \sim +85^{\circ}\text{C}^{*1}$)

- Input pulse levels: VIL = 0.6V, VIH = 2.4V
- Input rise and fall time: 5ns
- Input and output timing reference level: 1.5V
- Output load: See figures (Including scope and jig)



Note 1. Ambient temperature range depends on R/I-version. Please see table on page 1.

Read Cycle

Parameter	Cymbol	R1LP010	08E**-5**	R1LP010)8E**-7**	Unit	Note
Parameter	Symbol	Min.	Max.	Min.	Max.	Offic	Note
Read cycle time	t _{RC}	55	-	70	i	ns	
Address access time	t _{AA}	ı	55	1	70	ns	
Chin calcat access time	t _{ACS1}	ı	55	1	70	ns	
Chip select access time	t _{ACS2}	ı	55	1	70	ns	
Output enable to output valid	t _{OE}	ı	30	1	35	ns	
Output hold from address change	tон	5	-	10	i	ns	
Chin coloct to output in law 7	t _{CLZ1}	5	-	10	i	ns	2,3
Chip select to output in low-Z	t _{CLZ2}	5	-	10	i	ns	2,3
Output enable to output in low-Z	toLZ	5	-	5	-	ns	2,3
Chin decelerate autout in high 7	t _{CHZ1}	0	20	0	25	ns	1,2,3
Chip deselect to output in high-Z	t _{CHZ2}	0	20	0	25	ns	1,2,3
Output disable to output in high-Z	t _{OHZ}	0	20	0	25	ns	1,2,3

Write Cycle

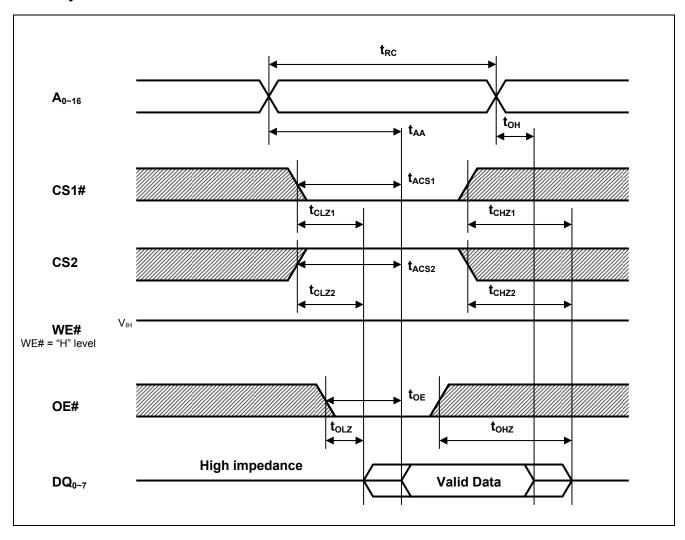
Parameter	Cumbal	R1LP010	08E**-5**	R1LP010)8E**-7**	Unit	Note
Parameter	Symbol	Min.	Max.	Min.	Max.	Offic	Note
Write cycle time	twc	55	-	70	-	ns	
Address valid to end of write	t _{AW}	50	-	55	-	ns	
Chip select to end of write	t _{CW}	50	-	55	-	ns	5
Write pulse width twp		45	-	50	-	ns	4
Address setup time	t _{AS}	0	-	0	-	ns	6
Write recovery time	t _{WR}	0	-	0	-	ns	7
Data to write time overlap	t _{DW}	25	-	30	-	ns	
Data hold from write time	t _{DH}	0	-	0	-	ns	
Output enable from end of write		5	-	5	-	ns	2
Output disable to output in high-Z t _{OHZ}		0	20	0	25	ns	1,2
Write to output in high-Z t _{WHZ}		0	20	0	25	ns	1,2

Note

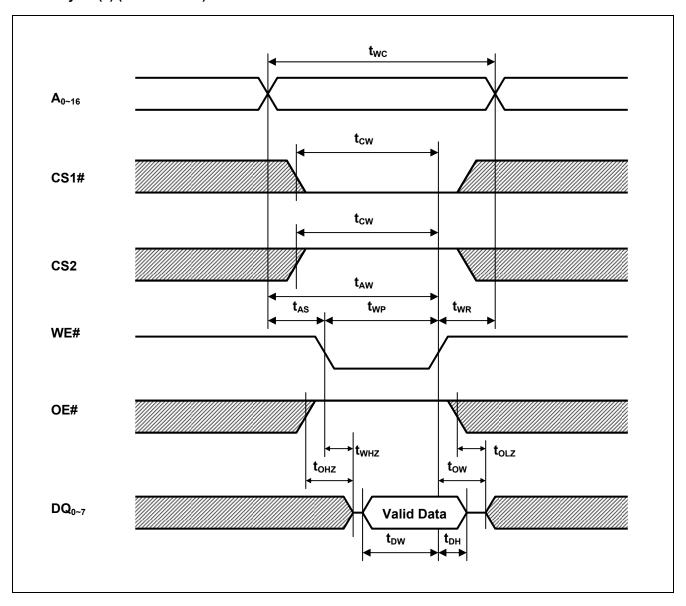
- 1. t_{CHZ} , t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.
- 2. This parameter is sampled and not 100% tested.
- 3. At any given temperature and voltage condition, t_{HZ} max is less than t_{LZ} min both for a given device and from device to device.
- 4. A write occurs during the overlap of a low CS1#, a high CS2, a low WE#.
 - A write begins at the latest transition among CS1# going low, CS2 going high and WE# going low.
 - A write ends at the earliest transition among CS1# going high, CS2 going low and WE# going high. t_{WP} is measured from the beginning of write to the end of write.
- 5. t_{CW} is measured from the later of CS1# going low or CS2 going high to end of write.
- 6. t_{AS} is measured the address valid to the beginning of write.
- 7. twR is measured from the earliest of CS1# or WE# going high or CS2 going low to the end of write cycle.
- 8. Don't apply inverted phase signal externally when DQ pin is output mode.

Timing Waveforms

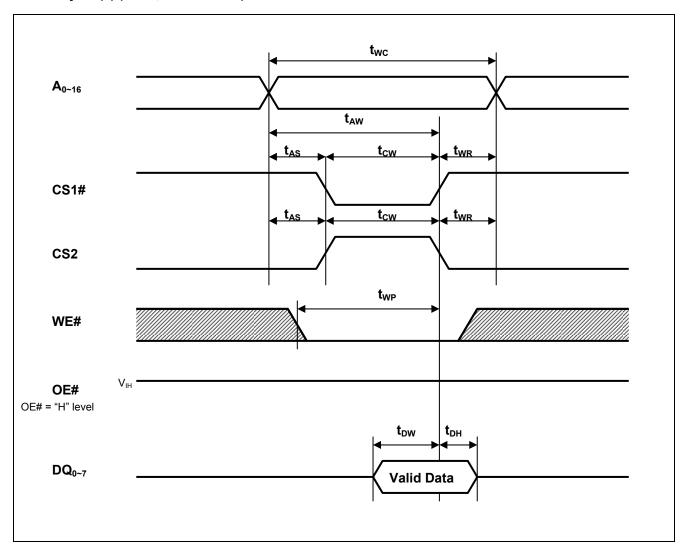
Read Cycle



Write Cycle (1) (WE# CLOCK)



Write Cycle (2) (CS1#, CS2 CLOCK)



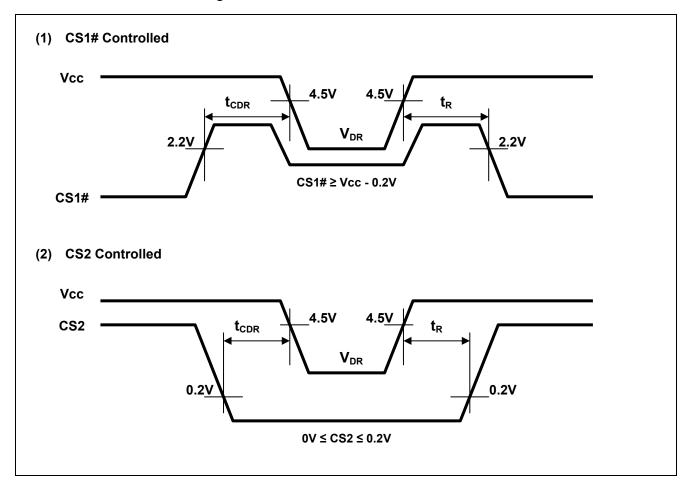
Low Vcc Data Retention Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit		Test conditions*2	
V _{CC} for data retention	V_{DR}	2.0	-	5.5	٧	Vin ≥ 0V (1) $0V \le CS2 \le 0.2V$ or (2) $CS1\# \ge Vcc-0.2V$, $CS2 \ge Vcc-0.2V$		
		-	0.6*1	2	μА	~+25°C	Vcc=3.0V, Vin ≥ 0V	
Data retention current	ICCDR	ı	-	3	μΑ	~+40°C	(1) 0V ≤ CS2 ≤ 0.2V or	
Data retention current		ı	-	8	μΑ	~+70°C	(2) CS1# ≥ Vcc-0.2V, CS2 ≥ Vcc-0.2V	
		-	-	10	μΑ	~+85°C		
Chip deselect time to data retention	t _{CDR}	0	-	-	ns	Soo roton	tion waveform	
Operation recovery time	t _R	5	-	-	ms	See retention waveform.		

Note 1. Typical parameter indicates the value for the center of distribution at 3.0V (Ta= 25°C), and not 100% tested.

2. CS2 controls address buffer, WE# buffer, CS1# buffer, OE# buffer and Din buffer. If CS2 controls data retention mode, Vin levels (address, WE#, CS1#, OE#, DQ) can be in the high impedance state.
If CS1# controls data retention mode, CS2 must be CS2 ≥ Vcc-0.2V or 0V ≤ CS2 ≤ 0.2V. The other input levels (address, WE#, OE#, DQ) can be in the high impedance state.

Low Vcc Data Retention Timing Waveforms



Revision History	R1LP0108E Series Data Sheet
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			Description					
Rev.	Date	Page	Summary					
1.00	2013.6.21	-	First Edition issued					

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